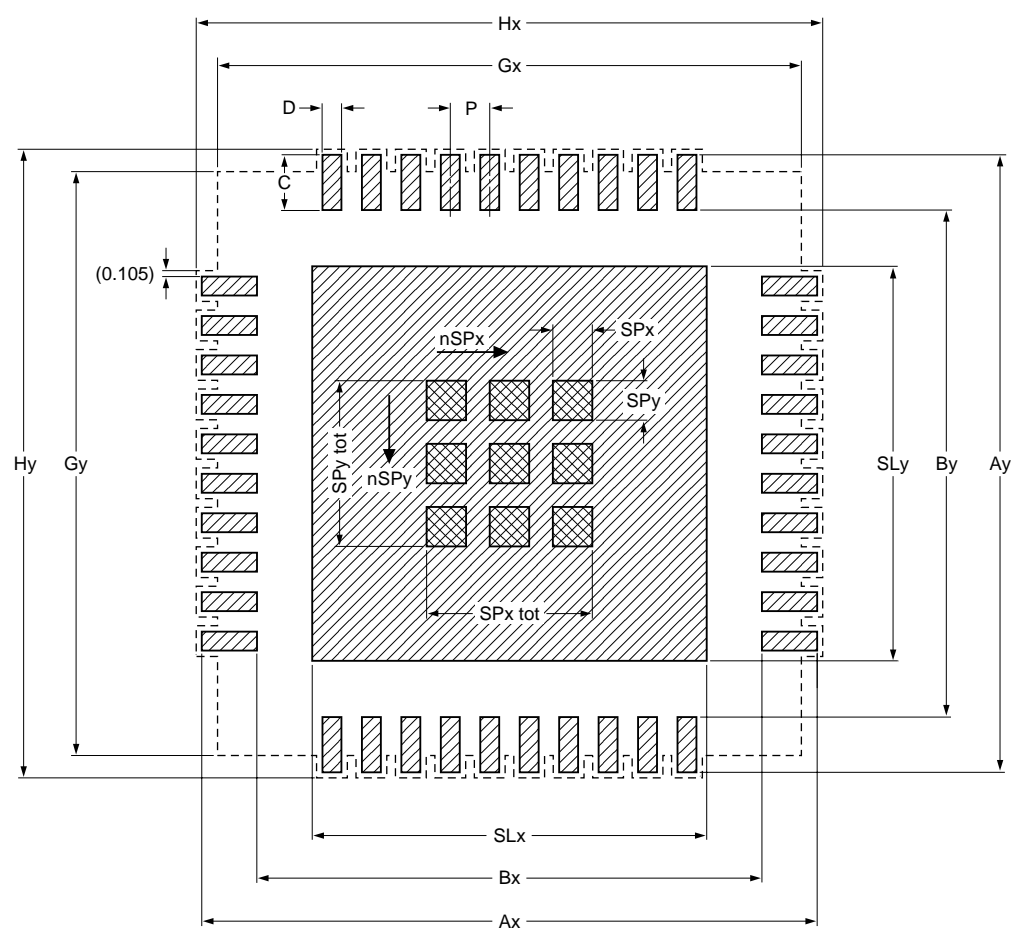


Footprint information for reflow soldering of HVQFN48 package

SOT619-1



- Generic footprint pattern
Refer to the package outline drawing for actual layout
- solder land
 - solder paste deposit
 - solder land plus solder paste
 - occupied area

nSPx	nSPy
3	3

DIMENSIONS in mm

P	Ax	Ay	Bx	By	C	D	SLx	SLy	SPx tot	SPy tot	SPx	SPy	Gx	Gy	Hx	Hy
0.500	8.000	8.000	6.200	6.200	0.900	0.290	5.100	5.100	3.000	3.000	0.750	0.750	7.300	7.300	8.250	8.250